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ABSTRACT OF THE DISCLOSURE

A thermosetting resin composition which contains:

(A) an epoxy resin having at least two epoxy groups per molecule;

(B) a hardener;

(C) a compound represented by the following general formula (1) or (2); and

(D) a microcapsule type hardening accelerator containing microcapsules each having a structure made up of a core containing a hardening accelerator and a shell covering the core and containing a polymer having a structural unit represented by the following general formula (3),

and which, when examined by differential scanning calorimetry at a heating rate of 10°C/min, shows an exothermic peak due to reaction in the range of from 180 to 250°C, and

a semiconductor device obtained through sealing with the composition are described.